

Leica TCS SP5 II

The Only Broadband Confocal

Technical Documentation



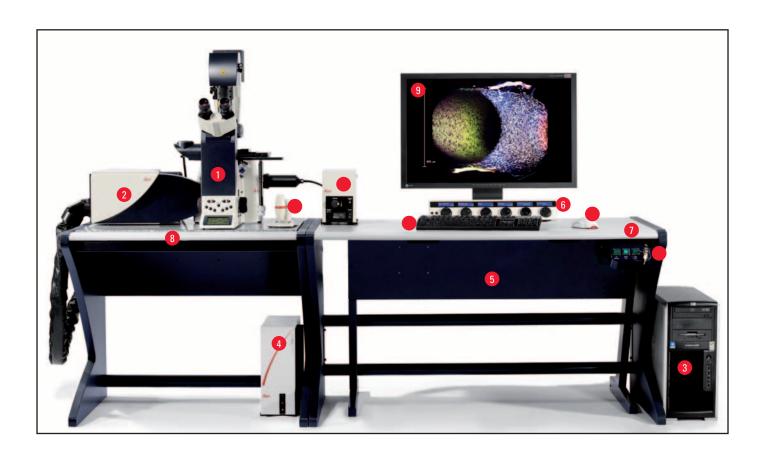
Specifications				
Microscopes	Upright	Leica DM6000 CS Leica DM6000 CFS		
	Inverted	Leica DMI6000 CS Leica DMI6000 CS bottom port		
Minner and without a debt	Specification	For imaging		
Microscope anti-vibration table	Vibration insulation	Passive		
	SuperZ galvanometer stage	1500 µm travel range/3 nm stepsize		
Z-drive	Motorfocus (stand)	Travel range depending on mechanics of microscope/15 nm step size		
	Laser type	For imaging		
	VIS	WLL, average power 1.5 mW: 470–670 nm		
		Diode, 40 mW: 442 nm		
		Ar, 65 mW: 458, 476, 488, 496, 514 nm		
Continuous wave lasers		HeNe, 1 mW: 543 nm		
Continuous wave factors		HeNe, 2 mW: 594 nm		
		HeNe, 10 mW: 633 nm		
		DPSS, 20 mW: 561 nm		
		UV OPSL, 80 mW: 355 nm		
	UV	Diode, 50 mW: 405 nm		
	Laser type	For imaging		
Pulsed lasers	IR	TiSa (ps or fs) 1 W 6901040 nm (various ranges)		
i uiseu iaseis	VIS	-		
	UV	_		
Excitation modulation	Modulation type	For imaging		
	AOTF VIS	Up to 8 channels		
	AOTF UV	Up to 3 channels		
	EOM IR	Yes		
	Pulsed laser driver	Optional		

	Features	For imaging
	Number of laser ports	Up to 3 (UV - VIS - IR)
	Number of lasers	Up to 8
	Excitation – emission splitting	Acousto Optical Beam Splitter (AOBS®) or dichroic beam splitters
	Detection range	400800 nm
	UV and IR imaging	Sequential or simultaneous
	Field upgradable	Yes (UV, IR)
Optics	UV correction	Individual precise correction optics (up to 5 positions)
	Pinhole	Alignment stable single pinhole
	Pinhole diameter control	Motorized by software, automatic mode available
	Switchable beam expander, optional	for DM6000/DMI6000: available for DM6000 CFS: not available
	Notch filters, optional	458 / 514 nm 488 / 561 / 633 nm
	Scanner design	For imaging
	Scanning concept	Optically correct scanning at low inertia
	Switch conventional – resonant scanner	Conventional and resonant scanner in one system (optional)
	Conventional scanner	For imaging (PMT and APD)
	Maximal line frequency	2800 Hz
	Minimal line frequency	1 Hz
Scanner	Scan speed granulation	1400
	Maximal frame rate 512 x 512	5 Hz
	Maximal frame rate 512 x 16	50 Hz
	Beam park	Yes
	Maximal frame resolution	8192 x 8192 pixel
	Scan zoom	1.0 64 x
	Panning	Yes
	Field rotation	200° optical
	Field diameter	22 mm

Scanner	Resonant scanner	For imaging
	Maximal line frequency	16000 Hz
	Minimal line frequency	8000 Hz
	Scan speed granulation	1
	Maximal frame rate 512 x 512	28 Hz
	Maximal frame rate 512 x 16	290 Hz
	Beam park	No
	Maximal frame resolution	1024 x 1024 pixel
	Scan zoom	1.7 64 x
	Panning	Yes
	Field rotation	200° optical
	Field diameter	15 mm
	Scan options	For imaging
	xt	Yes
	ху	Yes
	xyt	Yes
	хуλ	Yes
	xz	Yes
Scan modes	xzλ	Yes
	хуz	Yes
	χγzλ	Yes
	xyt	Yes
	xzt	Yes
	xyzt	Yes
	xytz	Yes

	Detection features	Up to 5 PMT for confocal imaging
Internal confocal detection	Emission separation	Highly sensitive prism spectral detector
	Maximum number of confocal channels	5
	Tunability of emission bands	Yes
	Spectral detection range	400 – 800 nm
	Tuning steps of emission bands	1 nm
	Minimal detection range	5 nm
	Sensors	High sensitivity low noise PMT: R 9624
	Digitization	12 or 18 bit per channel
	Max. grey resolution	16 bit imaging
	Read out frequency	40 MHz
External confocal detection	Detection features	2 APDs for confocal imaging
	Emission separation	User-exchangeable beam splitting filter cubes
	Confocal channels	2
	Sensors	APDs from PE (SPCM-AQRH series) or MPD (PDM series)
	Quantum efficiency	PE APD: wavelength dependent, typ. 65% @ 670 nm MPD APD: wavelength dependent, typ. 45% @ 550 nm
	Dark counts	PE APD: < 250 cps MPD APD: < 250 cps
	Jitter FWHM	Not relevant
	Dead time	Not relevant
	Detection types	For Imaging
Non-confocal detection	Transmitted light detector	Optional, allowing BF, DIC, Ph etc.
Non-comocal detection	Non descanned transmitted light channels	Up to 4 channels (MP)
	Non descanned reflected light channels	Up to 4 channels (MP)
	Devices	For imaging
	Scanner control	Digitally at high performance (FPGA, field programmable gate arrays)
	Trigger in/out functions	Yes
	Auxiliary data input channels	Up to 2
Electronics	Max channels in parallel	12
	Computer	High performance PC workstation
	Monitors	2 x 19" monitors or 1 x 30" monitor
	Integration of third party software	-
	-	Programmable control panel with LCD function & value display

	Devices	For imaging
Extensions	Fast ROI-spectrometer	Optional
	Auxiliary emission port	Optional
	Environment accessories	Various options
	General	Intuitive and guiding user interface
	Context sensitive online help system	Included
	Multi-dimensional data acquisition	Included
	Region of interest (ROI) scan	Included
Software (LAS AF)	Excitation line/frame sequential scan	Included
Contitue (EAC Al)	Emission spectrum recording	Included
	Quantification tools	Included
	Multi-color restoration, spectral unmixing	Included
	General time lapse experiment control tile scanning (mosaic scan)	Included
	Dedicated application wizards	For imaging
Software options (LAS AF)	Live Data Mode	Interactive data recording also allowing job sequencing and online evaluation
	Advanced Mark & Find	Combines Mark & Find with sophisticated 3D recordings, Live Data Mode etc.
	3D visualization	Maximum and other projections, simulated fluorescence process, rotation animations, stereo pairs, red-green anaglyphs, height color coded extended depth of focus images etc.
	Colocalization	Histogram based colocalization and area measurements
	Deconvolution	Deconvolution option for widefield and confocal images
	MicroLab	FRAP wizard, FRAPxt wizard, FLIP wizard, FRET SE wizard, FRET AB wizard etc.
	SMD FCS wizard	-
	SMD FLIM wizard	-
	Electrophysiology	Interactive data recording also allowing correlation of optical and electrical data



- Research Microscope
- 2 Scanhead
- Workstation
- 4 Microscope Control Unit
- 5 Laser Supply and Power Supply
- 6 Control Panel
- Computer Table
- 8 Anti-vibration Table
- 9 Monitor
- 10 Supply Control
- Smart Move
- 12 EL6000 Fluorescence Illumination
- 13 Keyboard
- Computer Mouse



visible and ultraviolet radiation:

LASER RADIATION

AVOID DIRECT EXPOSURE TO BEAM

VISIBLE ANDIOR INVISIBLE

LASER RADIATION

P<500mW \(\lambda = 350-650 \) nm

CLASS 3B LASER PRODUCT

IEC 60825-1: 1993 + A1:1997 + A2:2001

infrared radiation:

LASER RADIATION

AVOID EYE OR SKIN EXPOSURE TO DIRECT OR SCATTERED RADIATION

VISIBLE ANDIOR INVISIBLE LASER RADIATION

PK-4W 2.- 350-1050 nm

CLASS 4 LASER PRODUCT IEC 60825-1: 1993 + A1:1997 + A2:2001

Installation Requirements

Weight base system: VIS: max. 320 kg

UV: max. 428 kg

IR: Optical bench 900 x 1500 mm + ca. 280 kg

IR Laser System + ca. 100 kg

Heat load max.: VIS: 3,2 kW

UV: 0,5 kW IR: 1.5 kW

Separate cooling: UV laser, air-cooled heat exchanger

IR laser, air-cooled heat exchanger (chiller)

Electric apply: VIS lasers: 100 ... 240 V AC \pm 10 %

2 x 1600 VA, 50/60 Hz (Power input 1+2)

UV laser: 100 \dots 240 V AC \pm 10 %

750 VA, 50/60 Hz

IR laser: 100 \dots 240 V AC \pm 10 %

15 ... 10 A, 50/60 Hz

Chiller for IR laser: 110 V/230 V AC \pm 10 %

10 A/6 A, 50/60 Hz

Environment: Room temperature: +18 ... +25 °C

Avoid proximity to air conditioning equipment

Protect from dust

Room darkening recommended

